

AMENDMENTS TO THE CLAIMS

1. (previously presented) Scribe lines for increasing a utilizable area on a wafer, the wafer comprising a plurality of dies in various shapes, the
5 scribe lines comprising:

at least a first scribe line arranged in a first direction in a first gap of the dies, the first scribe line having a first width; and

- at least a second scribe line arranged in the first direction in a second gap of the dies, the second scribe line having a second width
10 narrower than the first width.

2. (original) The scribe lines of claim 1 wherein the first scribe line comprises at least an alignment mark for aligning elements on different
15 dies.

3. (original) The scribe lines of claim 1 wherein the first scribe line comprises at least a test key for performing a quality test on the dies.

4. (original) The scribe lines of claim 1 wherein the first width is
20 approximately between 100 and 500 micrometers.

5. (original) The scribe lines of claim 1 wherein the second width is approximately between 10 and 50 micrometers.

- 25 6. (original) The scribe lines of claim 1 wherein the second scribe line is provided for dicing the wafer.

7. (original) The scribe lines of claim 1 wherein the wafer is scribed by supplying a mechanical stress on the scribe lines.
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8. (original) The scribe lines of claim 1 wherein the wafer is scribed by performing an etching process on the scribe lines.

9. (original) The scribe lines of claim 1 further comprising a plurality of scribe lines arranged in a second direction, the scribe lines arranged in the second direction comprising various scribe line widths.

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10. (original) The scribe lines of claim 9 wherein the second direction is perpendicular to the first direction.

11. (canceled)

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12. (canceled)

13. (original) The scribe lines of claim 1 wherein the dies comprise various die sizes.

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14. (previously presented) Scribe lines on a wafer, the wafer comprising a plurality of dies in various sizes, the scribe lines comprising:

20 a plurality of first scribe lines positioned in gaps of the dies, each of the first scribe lines comprising a predetermined pattern; and

a plurality of second scribe lines positioned in gaps of the dies, the second scribe lines being narrower than the first scribe lines.

25 15. (original) The scribe lines of claim 14 wherein the predetermined pattern comprises an alignment mark for aligning elements on different dies.

16. (original) The scribe lines of claim 14 wherein the predetermined pattern comprises a test key for performing a quality test on the dies.

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17. (original) The scribe lines of claim 14 wherein the first scribe lines comprise at least an arranging direction.

18. (original) The scribe lines of claim 14 wherein the second scribe lines comprise at least an arranging direction.

5 19. (canceled)

20. (original) The scribe lines of claim 14 wherein the dies comprise various die shapes.

10 21. (canceled)

22. (previously presented) Scribe lines on a wafer, the wafer comprising a plurality of dies, the scribe lines comprising:

15 a plurality of first scribe lines arranged in a first direction in gaps of the dies, the first scribe lines being divided into at least a first group and a second group, each of the first scribe lines of the first group comprising a first pattern and a first width, and each of the first scribe lines of the second group comprising a second pattern and a second width; and

20 a plurality of second scribe lines arranged in the first direction in gaps of the dies, the second scribe lines being narrower than the first scribe lines;

wherein the values of the first width and the second width depend on the first pattern size and the second pattern size, respectively.

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23. (previously presented) The scribe lines of claim 22 wherein the first pattern comprises at least an alignment mark for aligning elements on different dies.

30 24. (previously presented) The scribe lines of claim 22 wherein the first pattern comprises at least a test key for performing a quality test on the dies.

25. (previously presented) The scribe lines of claim 22 wherein the second pattern comprises at least an alignment mark for aligning elements on different dies.

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26. (previously presented) The scribe lines of claim 22 wherein the second pattern comprises at least a test key for performing a quality test on the dies.

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27. (previously presented) The scribe lines of claim 22 wherein the second scribe lines are provided for dicing the wafer.

28. (previously presented) The scribe lines of claim 22 wherein the dies are in the same shapes and sizes.

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29. (previously presented) The scribe lines of claim 22 wherein the dies comprise various die shapes.

30. (previously presented) The scribe lines of claim 22 wherein the dies
20 comprise various die sizes.